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74HC73

Dual JK flip-flop with reset; negative-edge trigger

Rev. 04 — 19 March 2008

Product data sheet

1. General description

The 74HC73 is a high-speed Si-gate CMOS device that complies with JEDEC standard no. 7A. It is pin compatible with Low-power Schottky TTL (LSTTL).

The 74HC73 is a dual negative-edge triggered JK flip-flop featuring individual J, K, clock ($\overline{nCP}$) and reset ($\overline{nR}$) inputs; also complementary nQ and $n\overline{Q}$ outputs.

The J and K inputs must be stable one set-up time prior to the HIGH-to-LOW clock transition for predictable operation.

The reset ($\overline{nR}$) is an asynchronous active LOW input. When LOW, it overrides the clock and data inputs, forcing the nQ output LOW and the $n\overline{Q}$ output HIGH.

Schmitt-trigger action in the clock input makes the circuit highly tolerant to slower clock rise and fall times.

2. Features

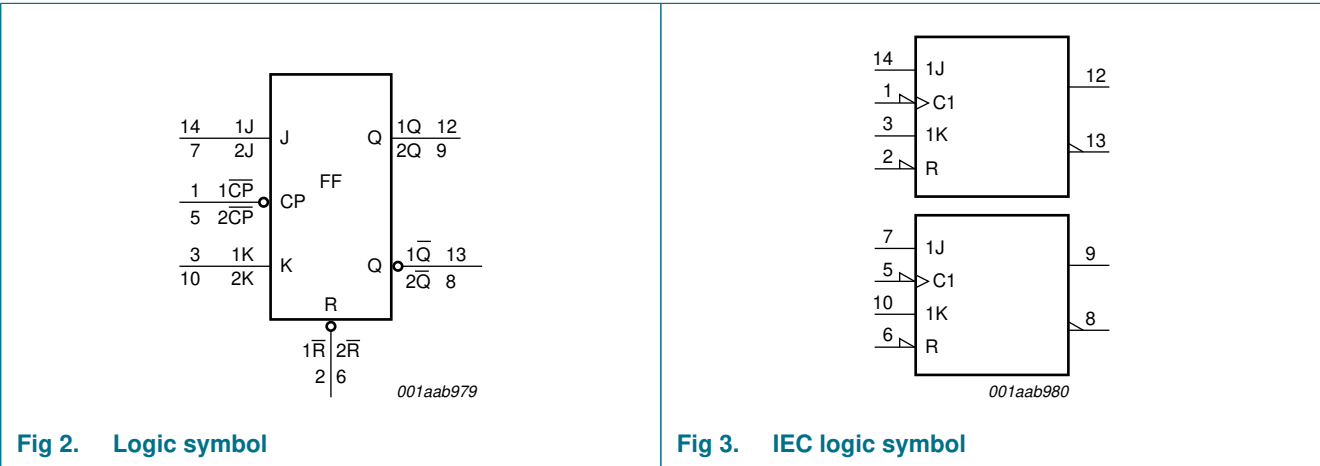
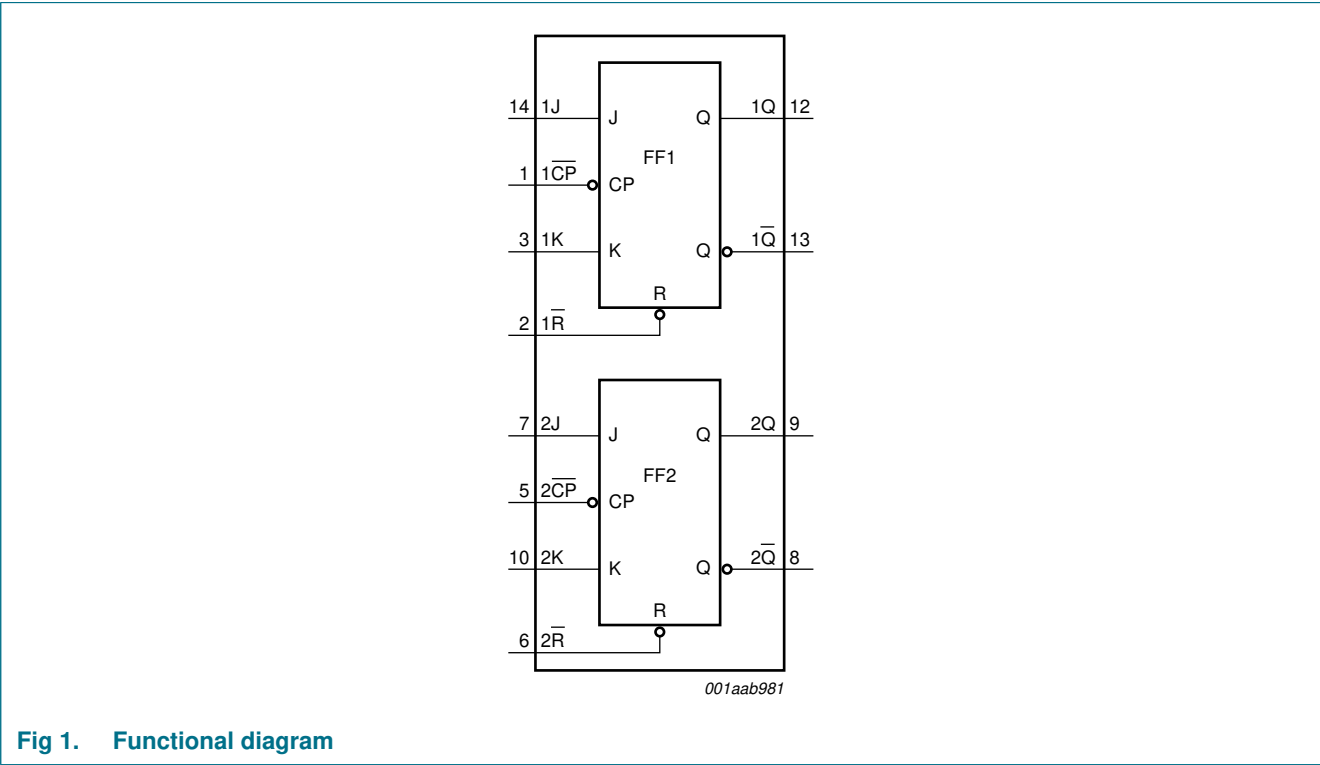
- Low-power dissipation
- Complies with JEDEC standard no. 7A
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+80\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC73N	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
74HC73D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74HC73DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74HC73PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1

4. Functional diagram



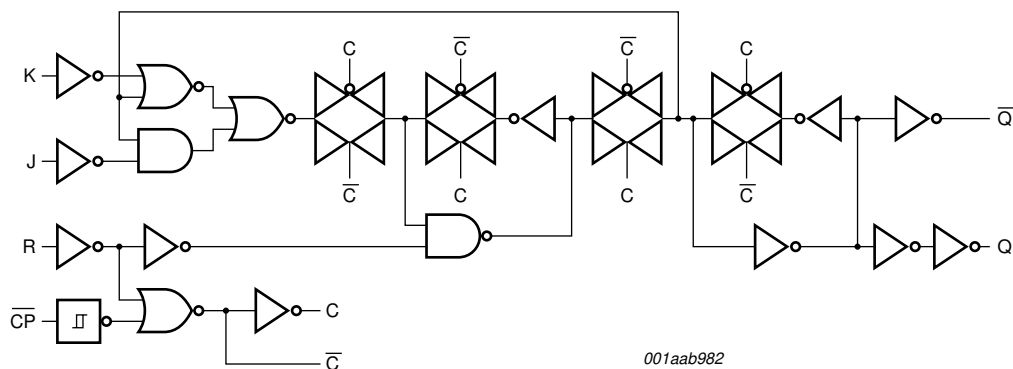


Fig 4. Logic diagram (one flip-flop)

5. Pinning information

5.1 Pinning

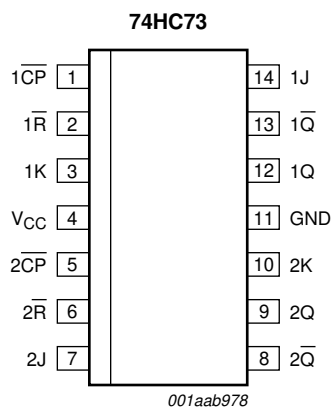


Fig 5. Pin configuration

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1CP, 2CP	1, 5	clock input (HIGH-to-LOW edge-triggered); also referred to as nCP
1R, 2R	2, 6	asynchronous reset input (active LOW); also referred to as nR
1K, 2K	3, 10	synchronous K input; also referred to as nK
VCC	4	positive supply voltage
GND	11	ground (0 V)
1Q, 2Q	12, 9	true output; also referred to as nQ
1Q-bar, 2Q-bar	13, 8	complement output; also referred to as nQ-bar
1J, 2J	14, 7	synchronous J input; also referred to as nJ

6. Functional description

Table 3. Function table^[1]

Input				Output		Operating mode
nR	nCP	nJ	nK	nQ	nQ	
L	X	X	X	L	H	asynchronous reset
H	↓	h	h	q	q	toggle
H	↓	l	h	L	H	load 0 (reset)
H	↓	h	l	H	L	load 1 (set)
H	↓	l	l	q	q	hold (no change)

- [1] H = HIGH voltage level;
 h = HIGH voltage level one set-up time prior to the HIGH-to-LOW clock transition;
 L = LOW voltage level;
 l = LOW voltage level one set-up time prior to the HIGH-to-LOW clock transition;
 q = state of referenced output one set-up time prior to the HIGH-to-LOW clock transition;
 X = don't care;
 ↓ = HIGH-to-LOW clock transition.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7.0	V
I _{IK}	input clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V	[1] -	±20	mA
I _{OK}	output clamping current	V _O < -0.5 V or V _O > V _{CC} + 0.5 V	[1] -	±20	mA
I _O	output current	V _O = -0.5 V to V _{CC} + 0.5 V	-	±25	mA
I _{CC}	supply current		-	50	mA
I _{GND}	ground current		-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C			
		DIP14 package	[2] -	750	mW
		SO14 package	[3] -	500	mW
		(T)SSOP14 package	[4] -	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 [2] P_{tot} derates linearly with 12 mW/K above 70 °C.
 [3] P_{tot} derates linearly with 8 mW/K above 70 °C.
 [4] P_{tot} derates linearly with 5.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CC}	supply voltage		2.0	5.0	6.0	V
V _I	input voltage		0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 2.0 V	-	-	625	ns
		V _{CC} = 4.5 V	-	1.67	139	ns
		V _{CC} = 6.0 V	-	-	83	ns

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = -20 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = -20 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -20 μA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I _O = -4 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	I _O = -5.2 mA; V _{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
		V _I = V _{IH} or V _{IL}								
		I _O = 20 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
I _I	input leakage current	I _O = 4 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
		V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	4.0	-	40.0	-	80.0	μA
C _I	input capacitance		-	3.5	-	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

GND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit, see [Figure 8](#)

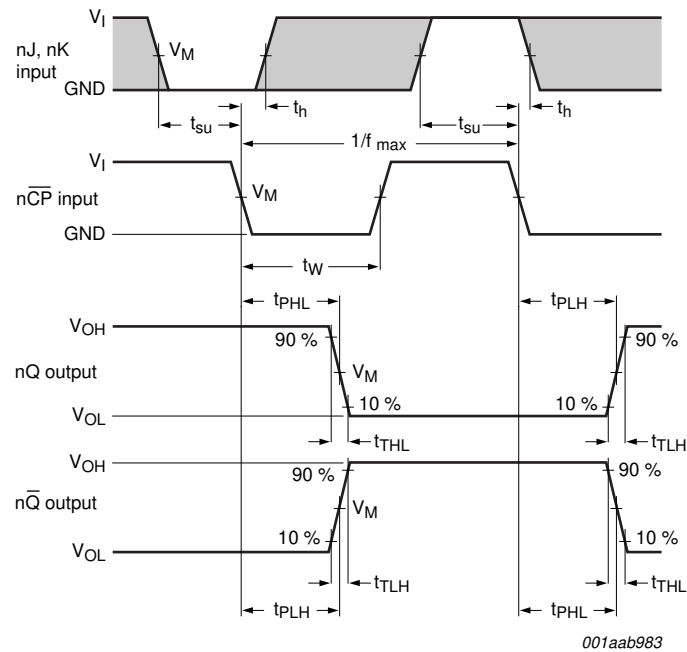
Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_{pd}	propagation delay	$\overline{nCP}$ to nQ; see Figure 6 ^[1]								
		$V_{CC} = 2.0$ V	-	52	160	-	200	-	240	ns
		$V_{CC} = 4.5$ V	-	19	32	-	40	-	48	ns
		$V_{CC} = 6.0$ V	-	15	27	-	34	-	41	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	16	-	-	-	-	-	ns
		$\overline{nCP}$ to $\overline{nQ}$; see Figure 6								
		$V_{CC} = 2.0$ V	-	52	160	-	200	-	240	ns
		$V_{CC} = 4.5$ V	-	19	32	-	40	-	48	ns
		$V_{CC} = 6.0$ V	-	15	27		34	-	41	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	16	-	-	-	-	-	ns
		$\overline{nR}$ to nQ, $\overline{nQ}$; see Figure 7								
		$V_{CC} = 2.0$ V	-	50	145	-	180	-	220	ns
		$V_{CC} = 4.5$ V	-	18	29	-	36	-	44	ns
		$V_{CC} = 6.0$ V	-	14	25		31	-	38	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	15	-	-	-	-	-	ns
t_t	transition time	nQ, $\overline{nQ}$; see Figure 6 ^[2]								
		$V_{CC} = 2.0$ V	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0$ V	-	6	13		16	-	19	ns
t_w	pulse width	$\overline{nCP}$ input, HIGH or LOW; see Figure 6								
		$V_{CC} = 2.0$ V	80	22	-	100		120	-	ns
		$V_{CC} = 4.5$ V	16	8	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	6	-	17	-	20		ns
		$\overline{nR}$ input, HIGH or LOW; see Figure 7								
		$V_{CC} = 2.0$ V	80	22	-	100		120	-	ns
		$V_{CC} = 4.5$ V	16	8	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	6	-	17	-	20		ns
t_{rec}	recovery time	$\overline{nR}$ to $\overline{nCP}$; see Figure 7								
		$V_{CC} = 2.0$ V	80	22	-	100		120	-	ns
		$V_{CC} = 4.5$ V	16	8	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	6	-	17	-	20		ns
t_{su}	set-up time	nJ, nK to $\overline{nCP}$; see Figure 6								
		$V_{CC} = 2.0$ V	80	22	-	100		120	-	ns
		$V_{CC} = 4.5$ V	16	8	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	6	-	17	-	20		ns

Table 7. Dynamic characteristics ...continuedGND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit, see [Figure 8](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_h	hold time	nJ, nK to $\overline{nCP}$; see Figure 6								
		$V_{CC} = 2.0$ V	3	-8	-	3		3	-	ns
		$V_{CC} = 4.5$ V	3	-3	-	3	-	3	-	ns
		$V_{CC} = 6.0$ V	3	-2	-	3	-	3		ns
f_{max}	maximum frequency	$\overline{nCP}$ input; see Figure 6								
		$V_{CC} = 2.0$ V	6.0	23	-	4.8		4.0	-	MHz
		$V_{CC} = 4.5$ V	30	70	-	24	-	20	-	MHz
		$V_{CC} = 6.0$ V	35	83	-	28	-	24	-	MHz
C_{PD}	power dissipation capacitance	$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	77	-		-		-	MHz
		per flip-flop; $V_I = \text{GND to } V_{CC}$ [3]	-	30	-	-	-	-	-	pF

[1] t_{pd} is the same as t_{PHL} , t_{PLH} .[2] t_t is the same as t_{THL} , t_{TLH} .[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW). $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where: f_i = input frequency in MHz; f_o = output frequency in MHz; C_L = output load capacitance in pF; V_{CC} = supply voltage in V; N = number of inputs switching; $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms

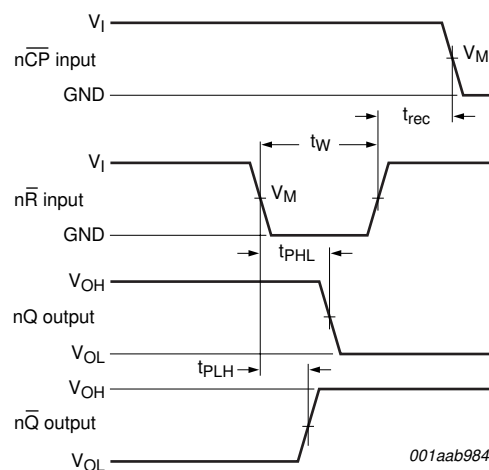


The shaded areas indicate when the input is permitted to change for predictable output performance.

Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Waveforms showing the clock ($\overline{nCP}$) to output (nQ , $\overline{nQ}$) propagation delays, the clock pulse width, the J and K to $\overline{nCP}$ set and hold times, the output transition times and the maximum clock frequency



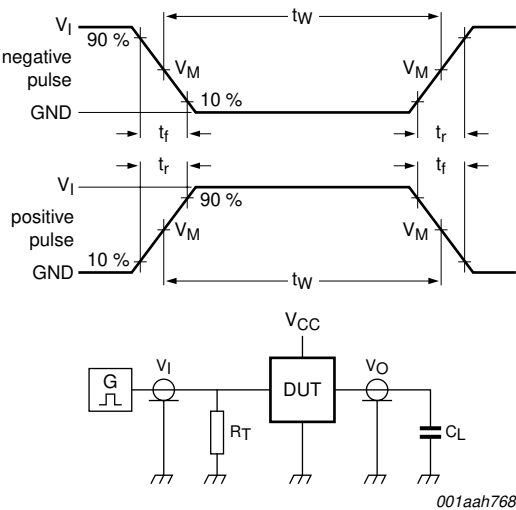
Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 7. Waveforms showing the reset ($\overline{nR}$) input to output (nQ , $\overline{nQ}$) propagation delays and the reset pulse width and the $\overline{nR}$ to $\overline{nCP}$ removal time

Table 8. Measurement points

Type	Input		Output
	V_I	V_M	V_M
74HC73	V_{CC}	$0.5V_{CC}$	$0.5V_{CC}$



Test data is given in [Table 9](#).
Definitions for test circuit:
 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.
 C_L = Load capacitance including jig and probe capacitance.

Fig 8. Test circuit for measuring switching times

Table 9. Test data

Type	Input		Load
	V_I	t_r, t_f	C_L
74HC73	V_{CC}	6 ns	15 pF, 50 pF

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

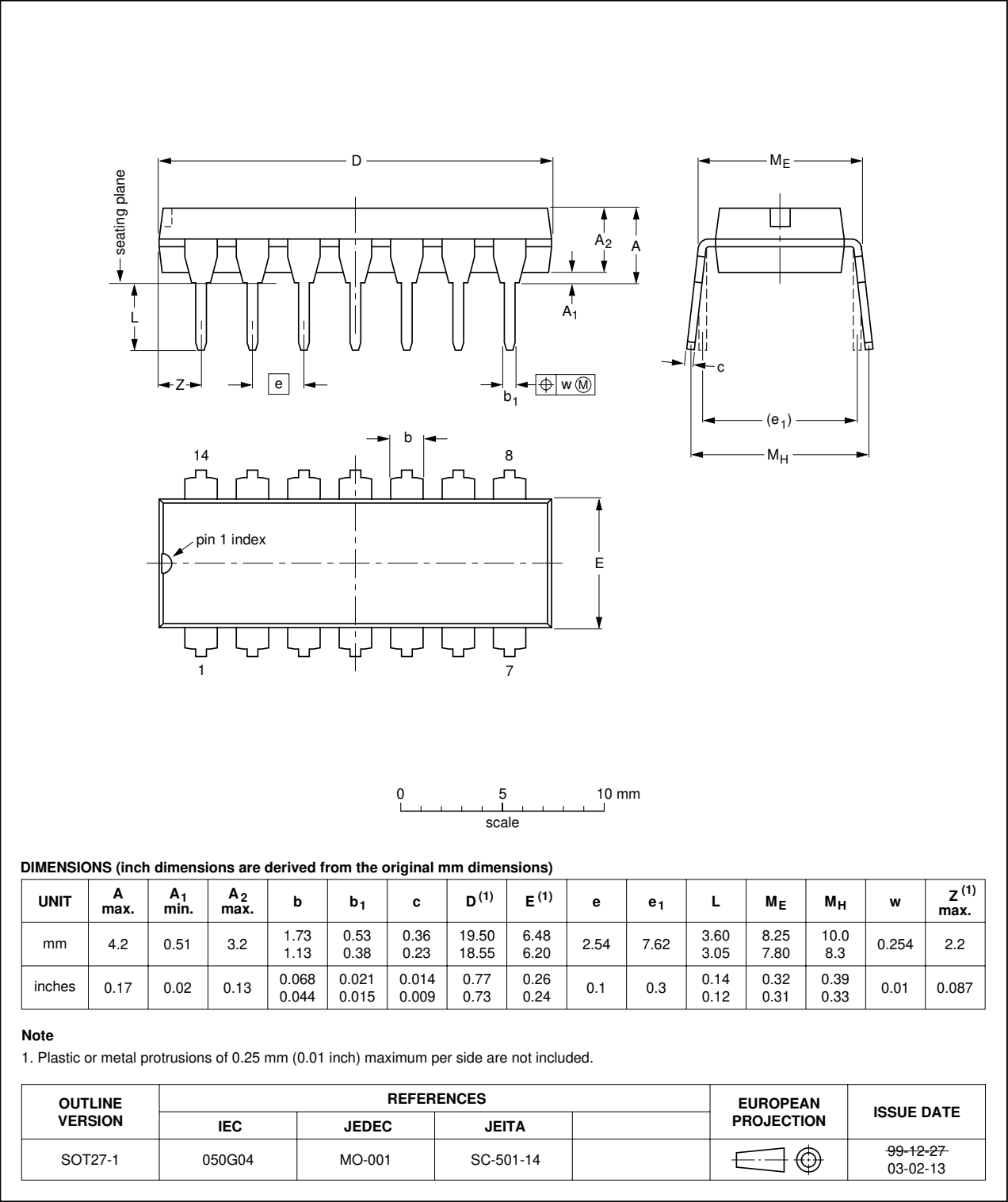


Fig 9. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

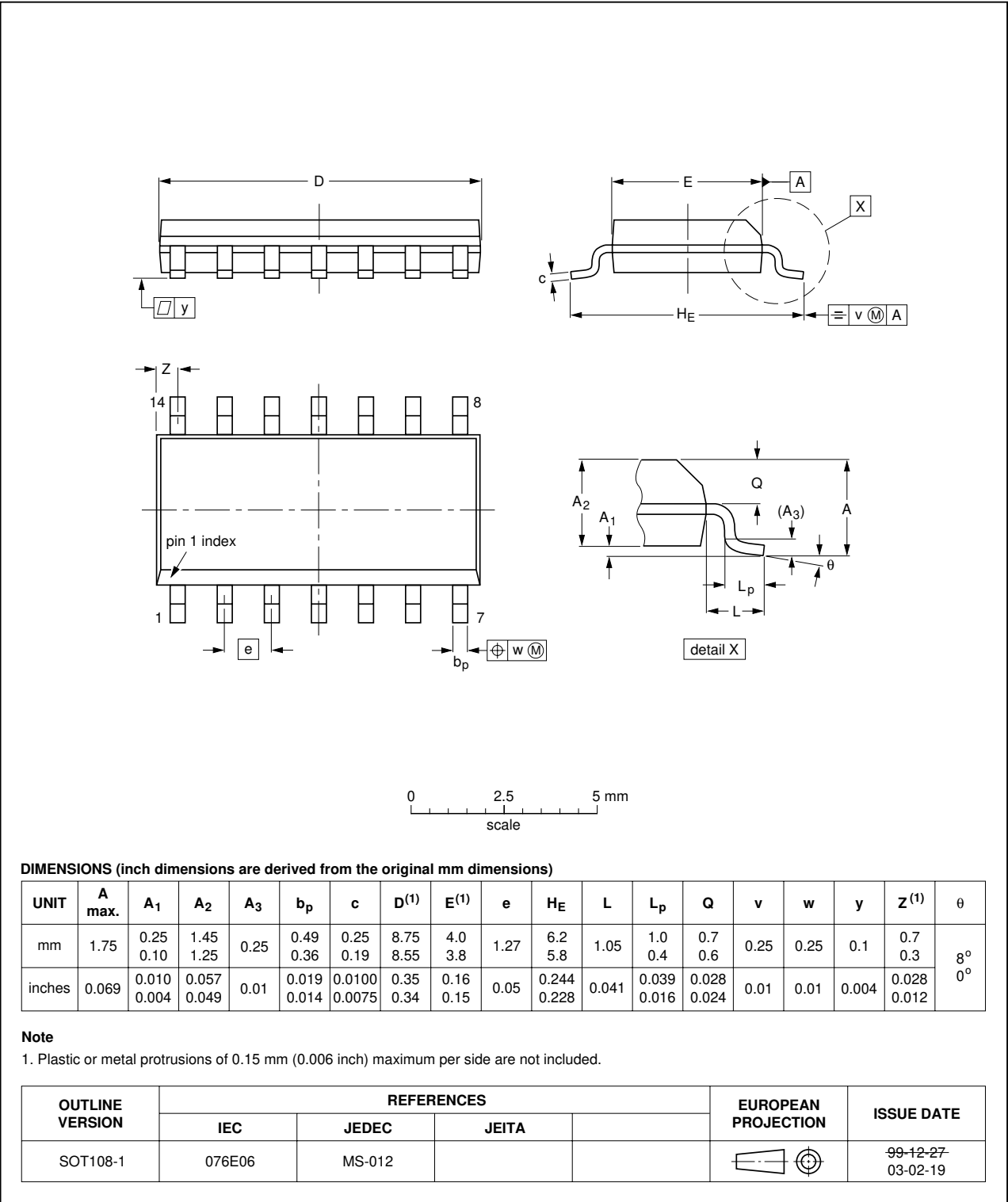


Fig 10. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

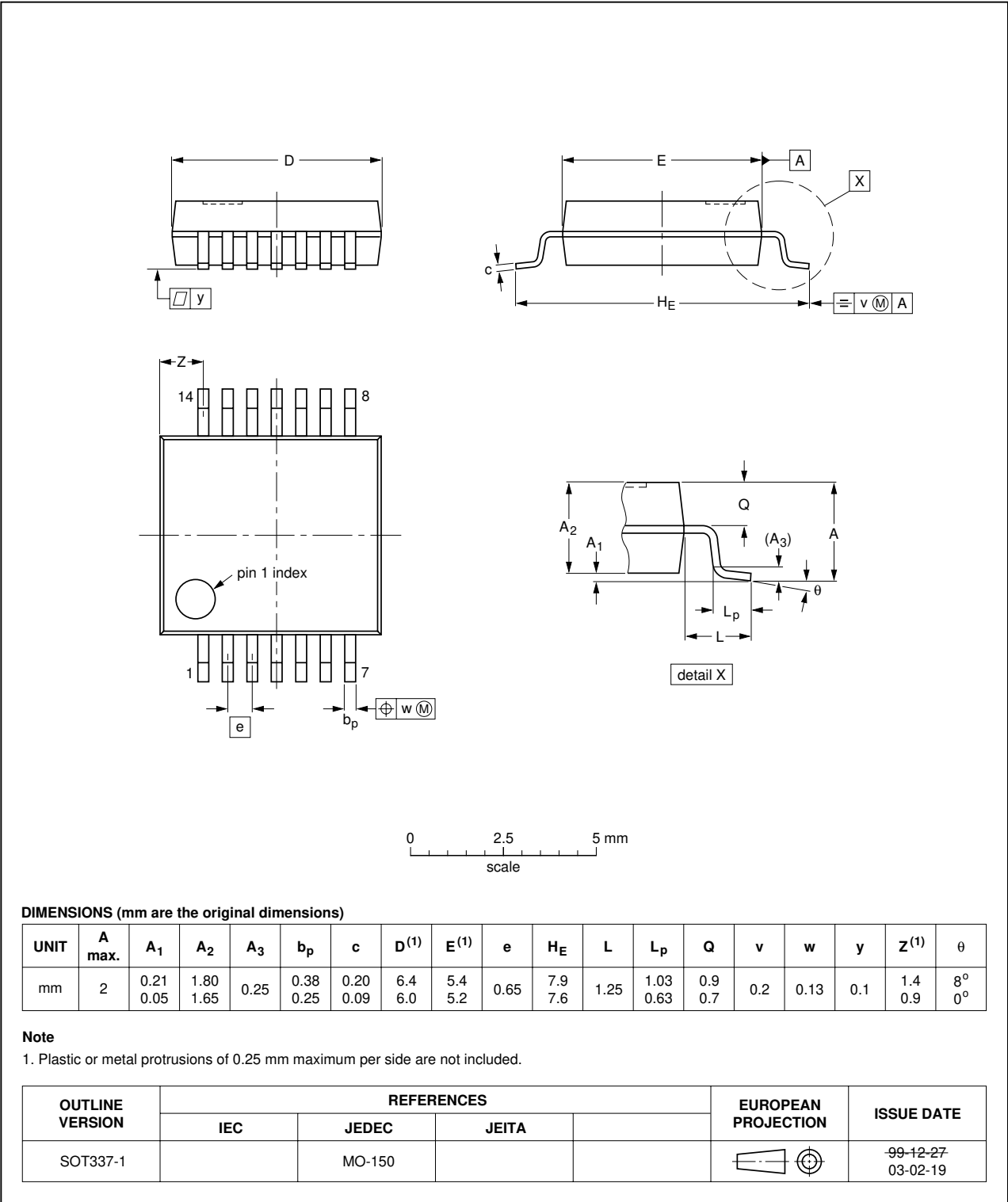


Fig 11. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

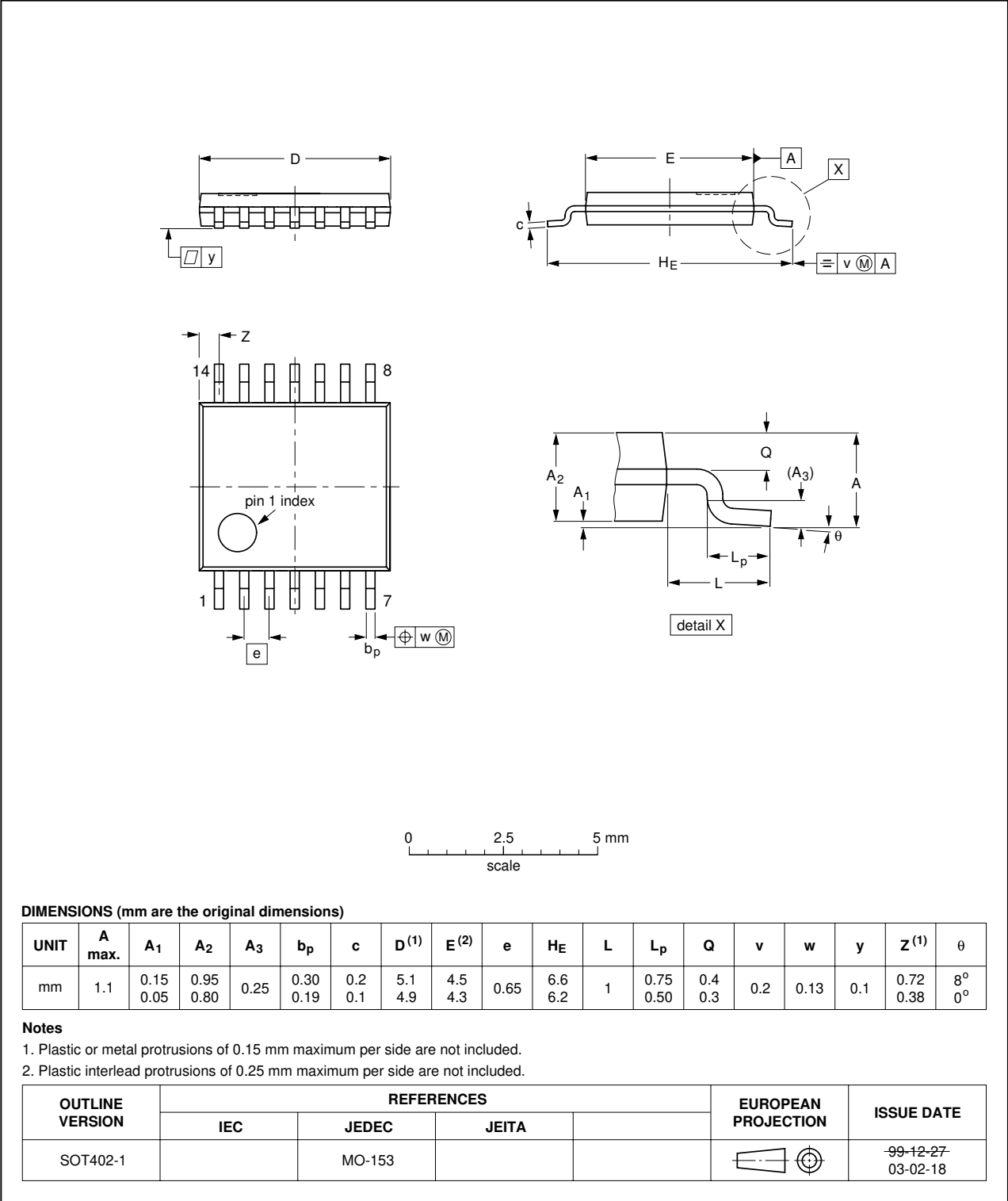


Fig 12. Package outline SOT402-1 (TSSOP14)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC73_4	20080319	Product data sheet	-	74HC73_3
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Quick reference data incorporated into Section 9 and 10. • Section 8 "Recommended operating conditions" t_r, t_f converted to $\Delta t/\Delta V$.			
74HC73_3	20041112	Product data sheet	-	74HC_HCT73_CNV_2
74HC_HCT73_CNV_2	December 1990	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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